HCI 4.0mm Pitch wire to board Connectors

1. SCOPE

This specification is covered the crimping requirements for HCI 4.0mm Pitch wire to board Connectors.

2. Applicable Products

Applicable product numbers are written below.

Part No.	Description
2420268-X	HCI 4.0mm Pitch wire to board socket contact

Fig.1 Part No. list

3. Crimping Requirements

3.1 Crimping Condition

Wire Size (AWG)	Part Number	Insulation O.D (mm)	Conductor (mm)	Insulation (mm)
			Crimp height (A)	Crimp height (B)
20	2420268-1	1.7~3.2	1.05±0.05	3.0
18			1.10±0.05	3.0
16			1.20±0.05	3.2
26	2420268-2	1.3~2.4	0.78±0.05	2.45
24			0.83±0.05	2.55
22			0.88±0.05	2.65

Fig.2 Crimping Condition List

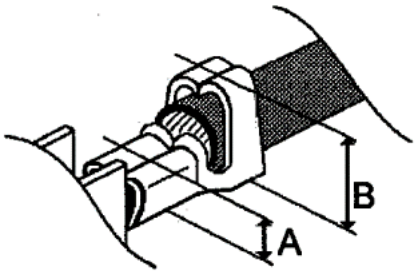


Fig.3 Crimping Image

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3.2 Standard Insulation Crimping Condition

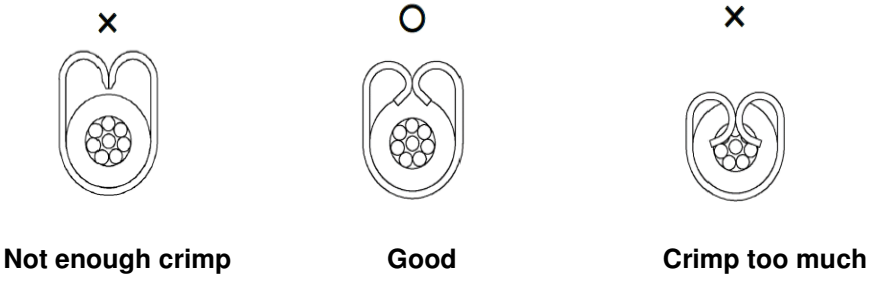


Fig.4 Insulation Crimping Image in cross

3.3 Standard Conductors Crimping



Fig.5 Conductor Crimping Image in cross section
(In case of flat bottom shape)

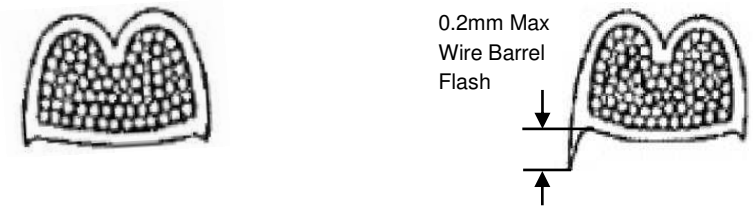


Fig.6 Conductor Crimping Image in cross section
(In case of not flat bottom shape)

3.4 Standard Terminal Crimping

Item	Range (Ref)
Bend-up（Max.）	3°
Bend-down（Max.）	3°
Twist（Max.）	4°
Rolling（Max.）	6°
Bellmouth length	0.1~0.4mm
Carrier cut off length	0~0.3mm
Wire-End Protrusion Length	0.5~1mm

Bend-up

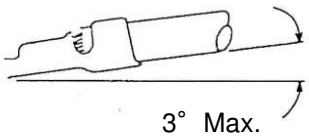


Fig.7-1

Bend-down

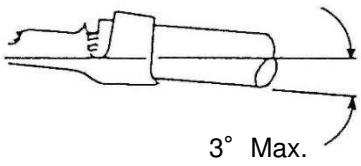


Fig.7-2

Twisting

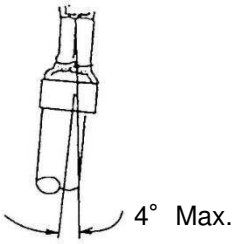


Fig.8-1

Twisting

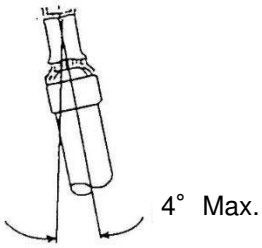


Fig.8-2

Rolling

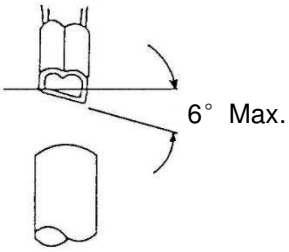


Fig.9-1

Rolling

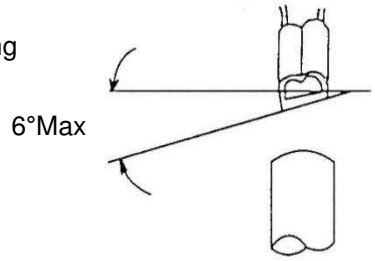
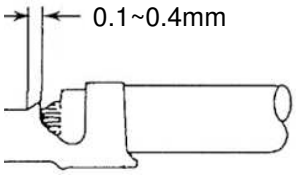
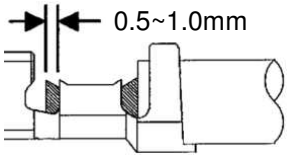
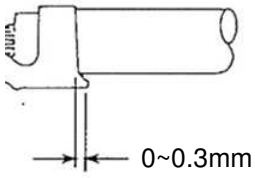


Fig.9-2

Bellmouth Length  Fig.10	Wire-End Protrusion Length  Fig.11
Carrier Cut-Off Length  Fig.12	